

REMARKS

Claims 1-16 remain in this application, claims 6-14 have been objected to, and claims 1-5, 15, and 16 have been rejected. Claims 17-20 have been added.

The Examiner has objected to claims 6-14 as being dependent upon a rejected base claim and has acknowledged that claims 6-14 "would be allowable if rewritten in independent form from including all of the limitations of the base claim." Accordingly, new claims 17-20 correspond to claims 6-14, which have been rewritten in independent form to include all of the limitations of the base claim. Thus, the new claims 17-20 are in proper form for allowance.

The Examiner has rejected claims 1-4, 15, and 16 under 35 U.S.C. 102(b) as being anticipated by U.S. Patent Number 5,947,753 ("Chapman"). Additionally, the Examiner has rejected claim 5 under 35 U.S.C. 103(a) as being unpatentable over Chapman in combination with U.S. Patent Number 5,837,950.

Claims 1 and 15, which are the only independent claims, are directed to an electrical device that is limited to an electrical apparatus positioned within a housing formed of heat conductive material, a flexible printed circuit board attached to at least a portion of the exterior of the housing, and at least one heat-generating electrical component mounted on the outside surface of the flexible printed circuit board. Although the Examiner has alleged that each one of these limitations is disclosed by Chapman in "Fig. 2 & 5 col. 5, lines 41-67," Chapman does not disclose any of the above-listed limitations.

First, Chapman does not disclose an electrical apparatus being positioned in a heat conductive housing. Chapman discloses "a frame or heatsink 10," which can be seen in Figs. 2 and 5, that is sandwiched between two "printed circuit boards 8 and 9." *See* Col. 5, Lines 43-45. However, none of the figures show, nor does the text describe, any type of electrical apparatus that can be placed in the frame 10.

Second, Chapman does not disclose a flexible printed circuit board being attached to at least a portion of the exterior of the housing. The flexible printed circuit boards that are disclosed in Chapman are used for connecting pairs of rigid circuit boards. For example, in the "Detailed Description of the Preferred Embodiments" Chapman discloses that "the termination arrangement of this embodiment makes use of a pair of rigid intermediate circuit boards 14 and 15 connected to the main printed circuit boards by flexible circuit board interconnecting portions 16 and 17." *See* Col. 5, Lines 50-53. The flexible circuit boards 16 and 17, as can be clearly seen in Fig. 2, are not attached to any portion of the heatsink 10.

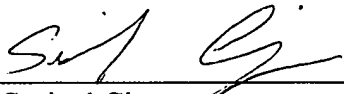
Third, Chapman fails to disclose a heat-generating electrical component being mounted on the flexible printed circuit board. Electrical components disclosed by Chapman are mounted on the main, rigid, circuit board. For example, Chapman refers to "a circuit board carrying electrical components" in the Abstract, and to "the circuit board on which the electrical components are situated" in the "Summary of the Invention" section. *See* Col. 3, Lines 59-60. Although the "Detailed Description of the Preferred Embodiments" does not clarify which circuit board is used for the mounting of the electrical components, claims 1 and 17 disclose "electronic components mounted on one surface of a rigid main circuit board." *See* Col. 11, Lines 51-52, and Col. 13, Lines 7-8. The "rigid main circuit board" refers to the "main circuit boards 8 and 9," which are shown in Fig. 2. *See*, Col. 5, Line 60. Thus, the electronic components disclosed by Chapman are mounted on a rigid circuit board. Chapman does not disclose, in text or figures, any electronic components being mounted on any one of the flexible circuit boards 16 and 17.

The Applicants respectfully submit that Chapman does not anticipate claims 1 and 15 at least for the reasons set forth above, and that claims 1 and 15 are in proper form for allowance. Furthermore, dependent claims 2-14 and 16 are in proper form for allowance at least for the same reasons as set forth above regarding claims 1 and 15.

Reconsideration of this application in light of the foregoing remarks is respectfully requested.

It is believed that no fee is presently due; however, should any additional fees be required (except for payment of the issue fee), the Commissioner is authorized to deduct the fees from Jenkins & Gilchrist, P.C. Deposit Account No. 10-0447, Order No. 47181-00252.

Respectfully submitted,

By 
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